

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	12215	(lap\$4 grind\$3 thin\$4 polish\$3 etch\$3) with (((back second opposite other) adj (side surface)) near5 (wafer\$1 substrate\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/26 08:45
L5	11809	(cu copper conductive metal\$1) with (((back second opposite other) adj (side surface)) near5 (wafer\$1 substrate\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/26 08:49
L6	348481	(dic\$3 singulat\$4 separat\$4 divid\$3 cut\$4) with (chip\$1 package\$1 die dice)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/26 08:53
L7	821	2 and 5 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/26 08:53
L8	380	7 and (solder adj (bump\$1 ball\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/26 08:57